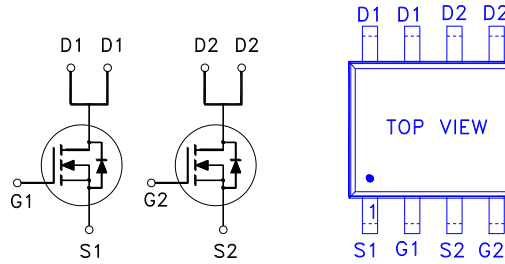


PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
150V	300m Ω	1.4A



G : GATE
D : DRAIN
S : SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	150	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_A = 25\text{ }^\circ\text{C}$	I_D	1.4	A
	$T_A = 70\text{ }^\circ\text{C}$		1.1	
Pulsed Drain Current ¹		I_{DM}	9	
Avalanche Current		I_{AS}	2.1	
Avalanche Energy	$L = 1\text{mH}$	E_{AS}	2.2	mJ
Power Dissipation	$T_A = 25\text{ }^\circ\text{C}$	P_D	1.5	W
	$T_A = 70\text{ }^\circ\text{C}$		0.9	
Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient ²	$R_{\theta JA}$		85	$^\circ\text{C} / \text{W}$

¹ Pulse width limited by maximum junction temperature.

² The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ }^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	150			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.3	1.7	2.3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 120\text{V}, V_{GS} = 0\text{V}$			1	μA
		$V_{DS} = 100\text{V}, V_{GS} = 0\text{V}, T_J = 55\text{ }^\circ\text{C}$			10	

Drain-Source On-State Resistance ¹	R _{DS(ON)}	V _{GS} = 4.5V, I _D = 1.4A	203	450	mΩ
		V _{GS} = 10V, I _D = 1.4A	199	300	
Forward Transconductance ¹	g _{fs}	V _{DS} = 10V, I _D = 1.4A	10		S

DYNAMIC					
Input Capacitance	C _{iSS}	V _{GS} = 0V, V _{DS} = 25V, f = 1MHz	611		pF
Output Capacitance	C _{oss}		42		
Reverse Transfer Capacitance	C _{rSS}		27		
Gate Resistance	R _g	V _{GS} = 0V, V _{DS} = 0V, f = 1MHz	1.4		Ω
Total Gate Charge ²	Q _g	V _{DS} = 75V, V _{GS} = 10V, I _D = 1.4A	14		nC
Gate-Source Charge ²	Q _{gs}		1.4		
Gate-Drain Charge ²	Q _{gd}		4		
Turn-On Delay Time ²	t _{d(on)}	V _{DD} = 75V I _D ≅ 1.4A, V _{GS} = 10V, R _{GEN} = 6Ω	11		nS
Rise Time ²	t _r		6.6		
Turn-Off Delay Time ²	t _{d(off)}		29		
Fall Time ²	t _f		6		

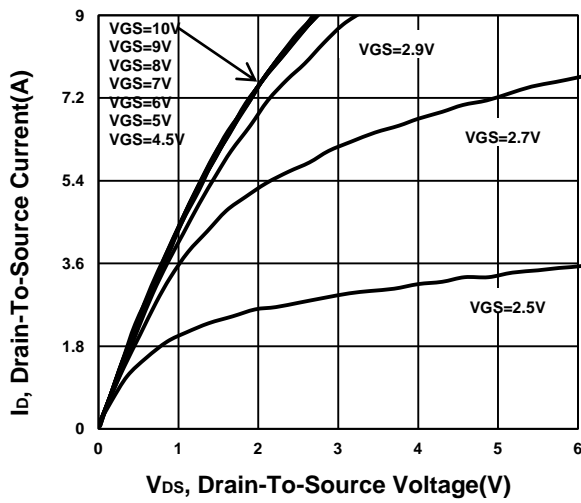
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T_J = 25 °C)

Continuous Current	I _S			1.6	A
Forward Voltage ¹	V _{SD}	I _F = 1.4 A, V _{GS} = 0V		1.3	V
Reverse Recovery Time	t _{rr}	I _F =1.4A, dI/dt=100A/μs	43		nS
Reverse Recovery Charge	Q _{rr}		21		uC

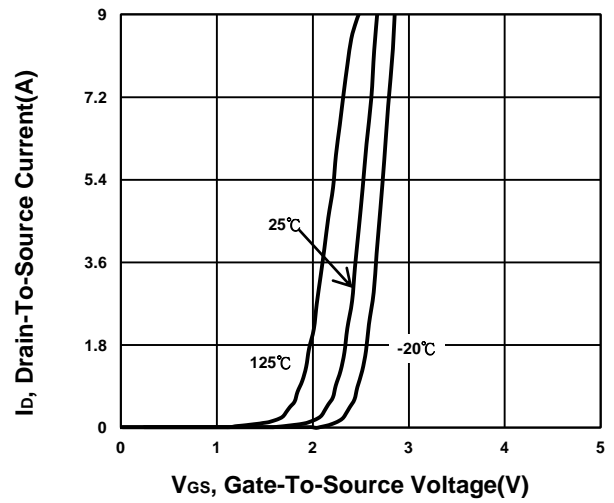
¹Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

²Independent of operating temperature.

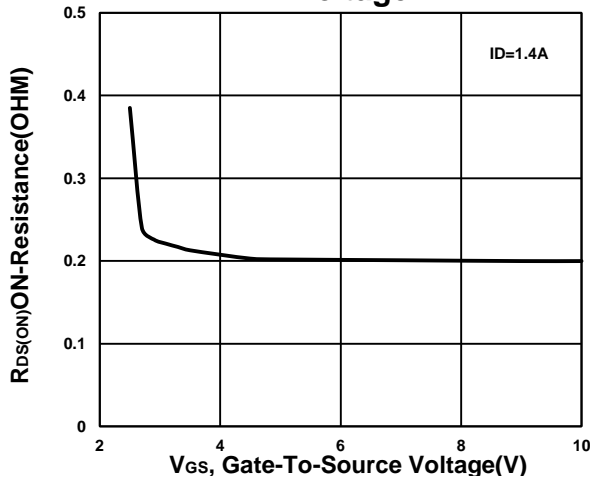
Output Characteristics



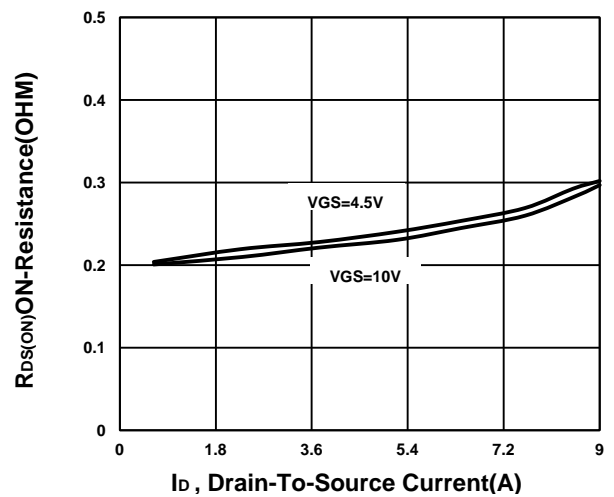
Transfer Characteristics



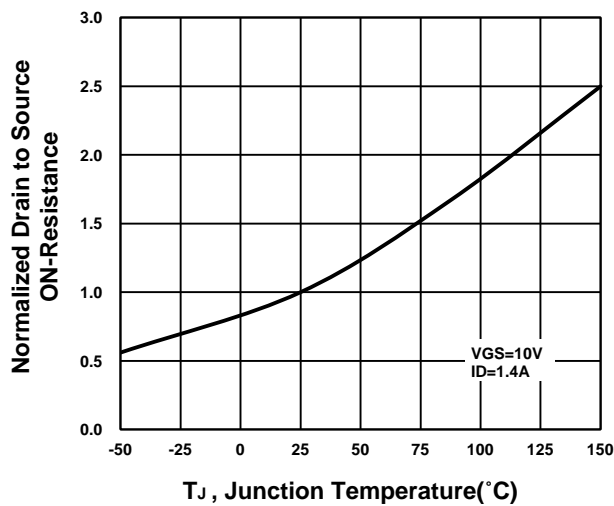
On-Resistance VS Gate-To-Source Voltage



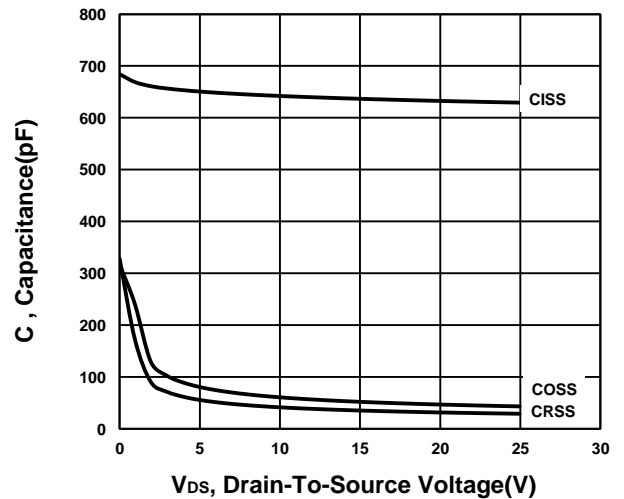
On-Resistance VS Drain Current



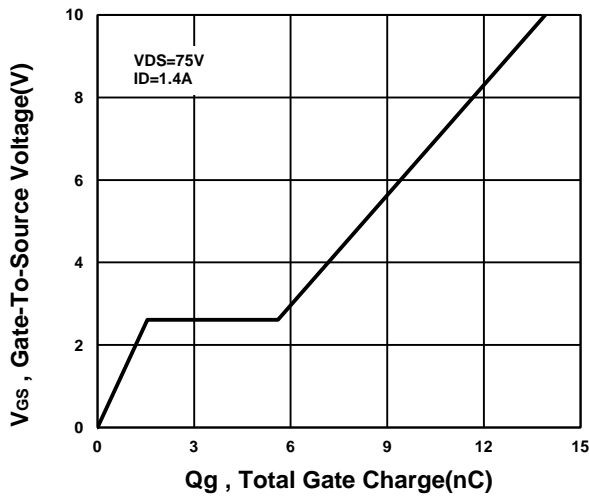
On-Resistance VS Temperature



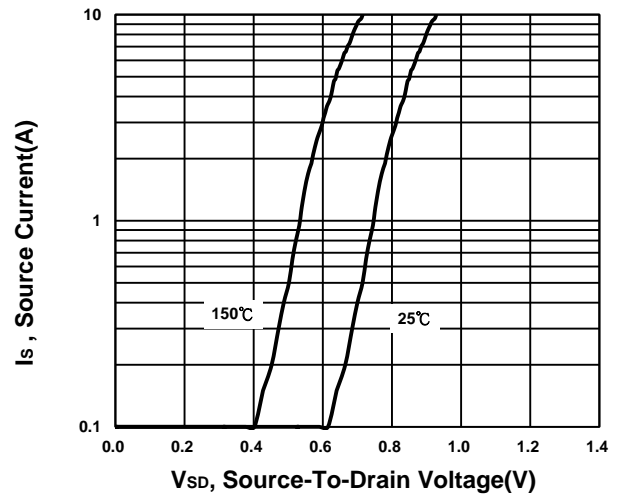
Capacitance Characteristic



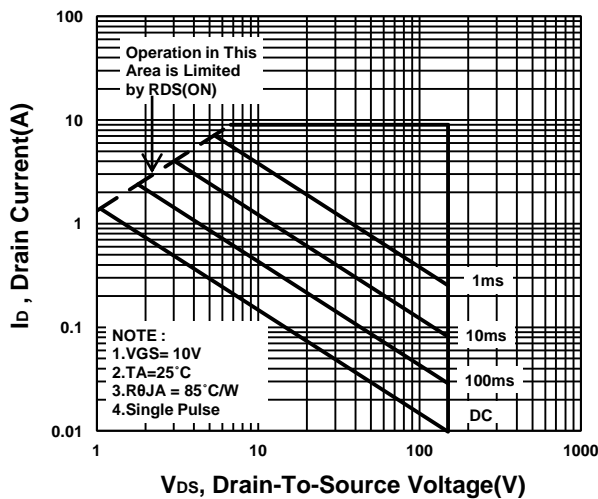
Gate charge Characteristics



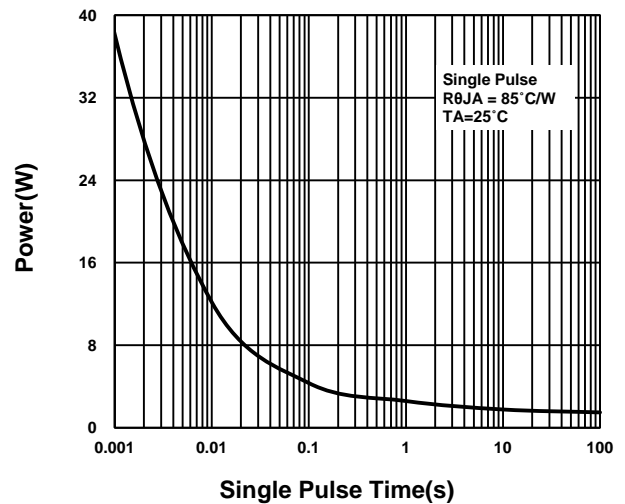
Source-Drain Diode Forward Voltage



Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

